



OPA356-Q1 200MHz CMOSオペアンプ

1 特長

- 車載アプリケーション向けに認定済み
- 下記内容でAEC-Q100認定済み
 - デバイス温度グレード: 動作時周囲温度範囲
–40°C~125°C
 - デバイスHBM ESD分類レベル2
 - デバイスCDM ESD分類レベルC6
- ユニティ・ゲイン帯域幅: 450MHz
- 広い帯域幅: 200MHz GBW
- 高いスルー・レート: 360V/μs
- 低ノイズ: 5.8nV/√Hz
- 非常に優れたビデオ性能
 - 差動ゲイン: 0.02%
 - 差動位相: 0.05°
 - 0.1dBのゲイン・フラットネス: 75MHz
- 入力範囲にグランドを含む
- レール・ツー・レール出力(100mV以内)
- 低い入力バイアス電流: 3pA
- サーマル・シャットダウン
- 単一電源電圧範囲: 2.5V~5.5V

2 アプリケーション

- インフォテインメント・システム
- ADASシステム
- レーダー
- 動的安定性制御(DSC)

3 概要

OPA356-Q1は高速の電圧帰還型CMOSオペアンプで、広い帯域幅を必要とするビデオおよびその他のアプリケーション用に設計されています。OPA356-Q1はユニティ・ゲイン安定で、大きな出力電流を駆動できます。差動ゲインは0.02%、差動位相は0.05°です。静止電流はわずか8.3mAです。

OPA356-Q1は、最低2.5V (±1.25V)、最高5.5V (±2.75V)のシングルまたはデュアル電源で動作するよう最適化されています。同相入力範囲はグランドより100mV下、V+より1.5V上までです。出力スイングはレールから100mV以内で、広いダイナミック・レンジに対応しています。

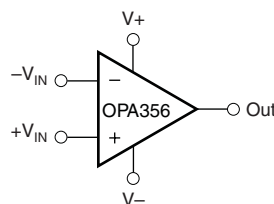
OPA356-Q1はSOT23-5パッケージで供給され、-40°C~125°Cの範囲で動作が規定されています。

製品情報⁽¹⁾

型番	パッケージ	本体サイズ(公称)
OPA356-Q1	SOT-23 (5)	2.90mm×1.60mm

(1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。

概略回路図



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4 改訂履歴

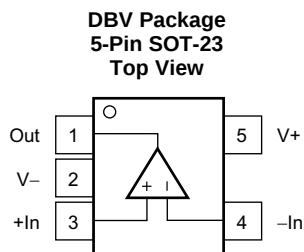
資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

2009年3月発行のものから更新

Page

• 「製品情報」表、「ESD定格」表、「熱に関する情報」表、「機能説明」セクション、「デバイスの機能モード」セクション、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクション 追加	1
• 「特長」にAEC-Q100認定済みの箇条書き項目を 追加	1
• Deleted <i>Ordering Information</i> table	3
• Deleted footnote 2 from <i>Absolute Maximum Ratings</i> table	4
• Deleted the SR, t_r , t_f , t_{settle} , and Overload recovery time rows from the <i>Electrical Characteristics</i> table and moved to the <i>Timing Requirements</i> table	5
• Changed <i>Layout Guidelines</i> title from <i>PCB Layout</i>	19

5 Pin Configuration and Functions



Pin Functions

PIN		I/O	DESCRIPTION
NO.	NAME		
1	Out	O	Output pin
2	V–	—	Negative power supply
3	+In	I	Noninverting input pin
4	–In	I	Inverting input pin
5	V+	—	Positive power supply

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

	MIN	MAX	UNIT
V _S Supply voltage, V+ to V–		7.5	V
V _{IN} Signal input pins voltage range	–0.5	(V+) + 0.5	V
V– current		10	mA
Output short-circuit duration ⁽²⁾		Continuous	
T _A Operating free-air temperature range	–40	125	°C
T _J Junction temperature		160	°C
T _{stg} Storage temperature	–65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Short-circuit to ground one amplifier per package.

6.2 ESD Ratings

	VALUE	UNIT
V _(ESD) Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 ⁽¹⁾	±2000
	Charged-device model (CDM), per AEC Q100-011	±500

- (1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

	MIN	MAX	UNIT
V _S Supply voltage, V– to V+	2.7	5.5	V
T _A Operating free-air temperature	–40	125	°C

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		OPA356-Q1	UNIT
		DBV (SOT-23)	
		5 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	185.0	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	102.5	°C/W
R _{θJB}	Junction-to-board thermal resistance	43.9	°C/W
ψ _{JT}	Junction-to-top characterization parameter	18.2	°C/W
ψ _{JB}	Junction-to-board characterization parameter	43.6	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	N/A	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

6.5 Electrical Characteristics

 $V_S = 2.7\text{ V to }5.5\text{ V}$, $R_F = 604\ \Omega$, $R_L = 150\ \Omega$ connected to $V_S / 2$ (unless otherwise noted)

PARAMETER			TEST CONDITIONS	T _A ⁽¹⁾	MIN	TYP	MAX	UNIT
V _{OS}	Input offset voltage		V _S = 5 V, V _{CM} = V _− + 0.8 V	25°C		±2	±9	mV
				Full range			±15	
ΔV _{OS} /ΔT	Offset voltage drift over temperature			Full range		±7		μV/°C
PSRR	Offset voltage drift vs power supply		V _S = 2.7 V to 5.5 V, V _{CM} = V _S / 2 − 0.15 V	25°C		±80	±350	μV/V
I _B	Input bias current			25°C		3	±50	pA
I _{OS}	Input offset current			25°C		±1	±50	pA
V _n	Input voltage noise density		f = 1 MHz	25°C		5.8		nV/√Hz
I _n	Input current noise density		f = 1 MHz	25°C		50		fA/√Hz
V _{CM}	Input common-mode voltage range			25°C	V _− − 0.1		V ₊ − 1.5	V
CMRR	Input common-mode rejection ratio		V _S = 5.5 V, −0.1 V < V _{CM} < 4 V	25°C	66	80		dB
				Full range	66			
Z _{ID}	Differential input impedance			25°C		10 ¹³ 1.5		Ω pF
Z _{ICM}	Common-mode input impedance			25°C		10 ¹³ 1.5		Ω pF
A _{OL}	Open-loop gain		V _S = 5 V, 0.3 V < V _O < 4.7 V	25°C	84	92		dB
				Full range	80			
f _{−3dB}	Small-signal bandwidth		G = 1, V _O = 100 mVp-p, R _F = 0 Ω	25°C		450		MHz
			G = 2, V _O = 100 mVp-p, R _L = 50 Ω			100		
			G = 2, V _O = 100 mVp-p, R _L = 150 Ω			170		
			G = 2, V _O = 100 mVp-p, R _L = 1 kΩ			200		
GBW	Gain-bandwidth product		G = 10, R _L = 1 kΩ	25°C		200		MHz
f _{0.1dB}	Bandwidth for 0.1-dB gain flatness		G = 2, V _O = 100 mVp-p, R _F = 560 Ω	25°C		75		MHz
SR	Slew rate		V _S = 5 V, G = 2, 4-V output step	25°C		+300		V/μs
						−360		
t _r , t _f	Rise and fall times		G = 2, V _O = 200 mVp-p, 10% to 90%	25°C		2.4		ns
			G = 2, V _O = 2 Vp-p, 10% to 90%			8		
t _{settle}	Settling time	0.1%	V _S = 5 V, G = 2, 2-V output step	25°C		30		ns
		0.01%				120		
Overload recovery time			V _{IN} × Gain = V _S	25°C		8		ns
Harmonic distortion	Second harmonic	G = 2, f = 1 MHz, V _O = 2 Vp-p, R _L = 200 Ω	25°C		−81		dBc	
	Third harmonic		25°C		−93			
Differential gain error			NTSC, R _L = 150 Ω	25°C		0.02%		
Differential phase error			NTSC, R _L = 150 Ω	25°C		0.05		°
Voltage output swing from rail			V _S = 5 V, R _L = 150 Ω, A _{OL} > 84 dB	25°C		0.2	0.3	V
			V _S = 5 V, R _L = 1 kΩ			0.1		
			V _S = 5 V, R _L = 50 Ω			0.4	0.6	
I _O	Output current ⁽²⁾	Continuous		25°C		±60		mA
		Peak	V _S = 5 V			±100		
			V _S = 3 V			±80		
Short-circuit current				25°C		+250		mA
						−200		
Closed-loop output impedance				25°C		0.02		Ω
I _Q	Quiescent current		V _S = 5 V, I _O = 0	25°C		8.3	11	mA
				Full range			14	
Thermal shutdown junction temperature			Shutdown	25°C		160		°C
			Reset from shutdown			140		

(1) Full range $T_A = -40^\circ\text{C to }125^\circ\text{C}$.

(2) See [Figure 20](#).

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6.6 Typical Characteristics

$T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $G = 2$, $R_F = 604\ \Omega$, $R_L = 150\ \Omega$ connected to $V_S / 2$ (unless otherwise noted)

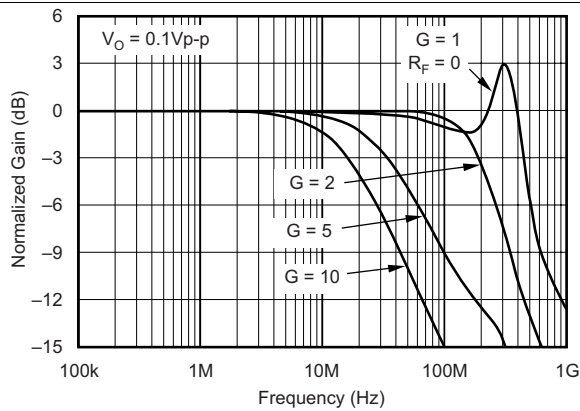


Figure 1. Noninverting Small-Signal Frequency Response

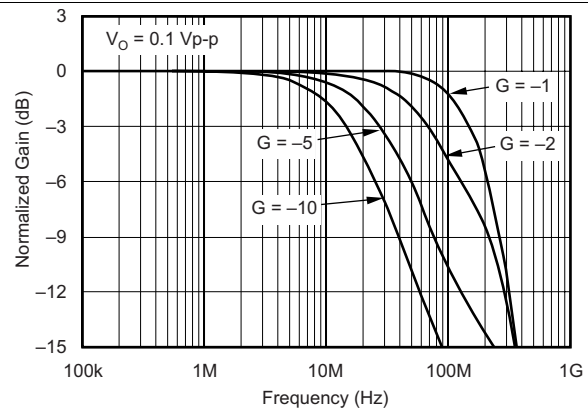


Figure 2. Inverting Small-Signal Frequency Response

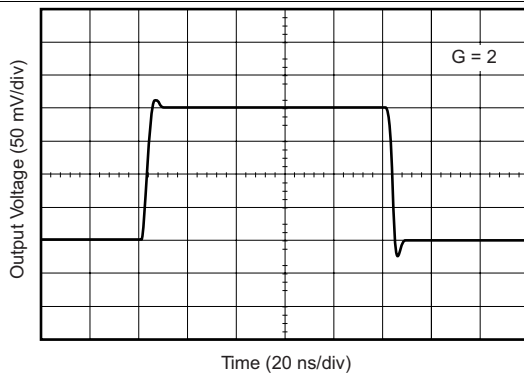


Figure 3. Noninverting Small-Signal Step Response

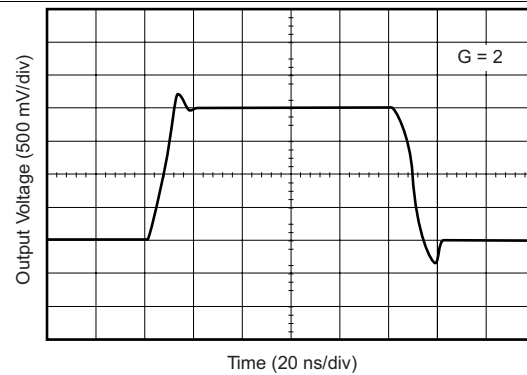


Figure 4. Noninverting Large-Signal Step Response

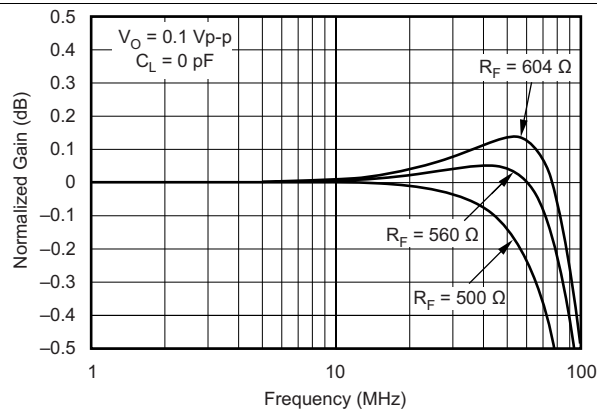


Figure 5. 0.1-dB Gain Flatness for Various R_F

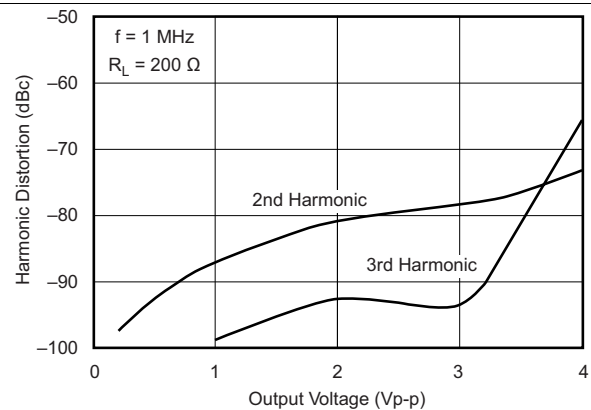


Figure 6. Harmonic Distortion vs Output Voltage

Typical Characteristics (continued)

$T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $G = 2$, $R_F = 604\ \Omega$, $R_L = 150\ \Omega$ connected to $V_S / 2$ (unless otherwise noted)

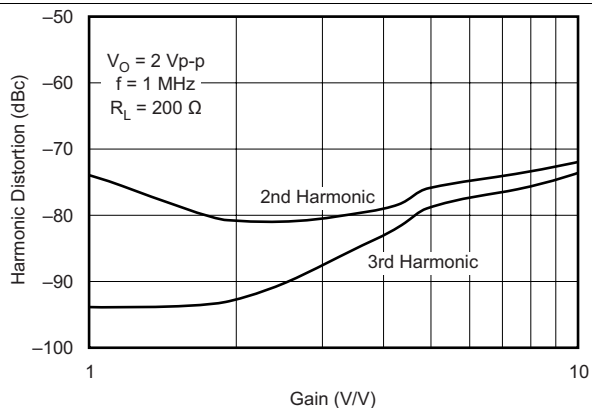


Figure 7. Harmonic Distortion vs Non-Inverting Gain

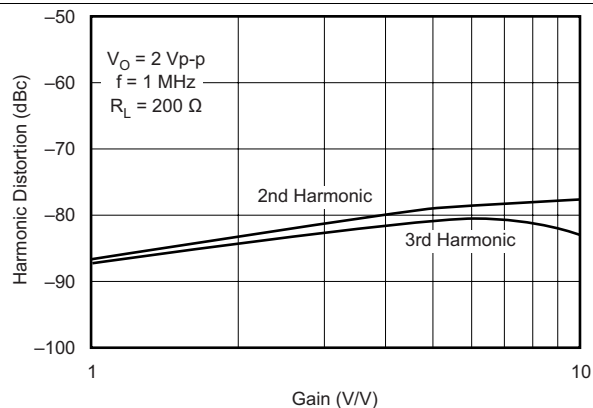


Figure 8. Harmonic Distortion vs Inverting Gain

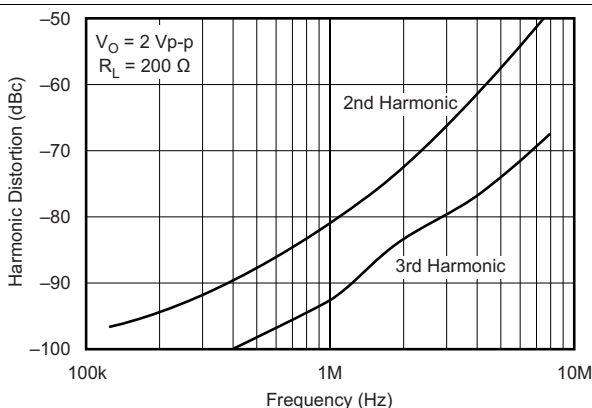


Figure 9. Harmonic Distortion vs Frequency

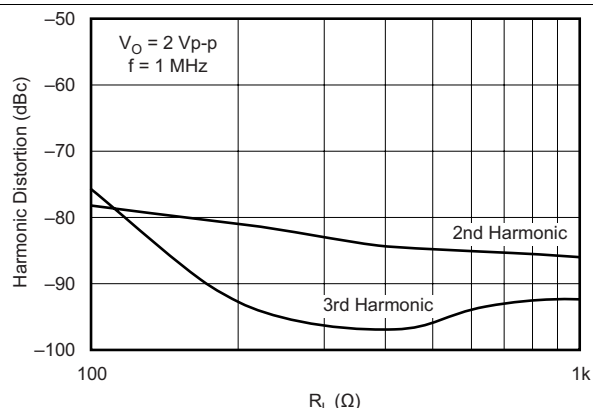


Figure 10. Harmonic Distortion vs Load Resistance

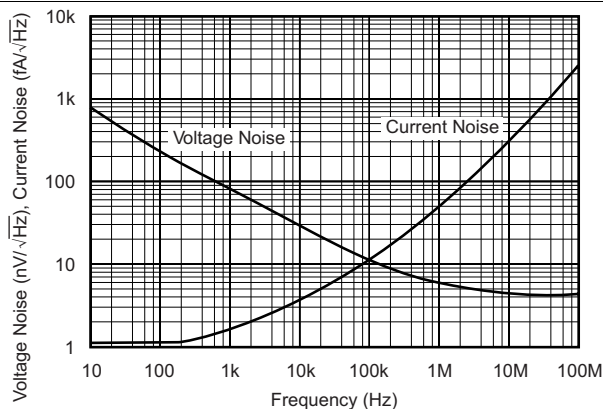


Figure 11. Input Voltage and Current Noise Spectral Density vs Frequency

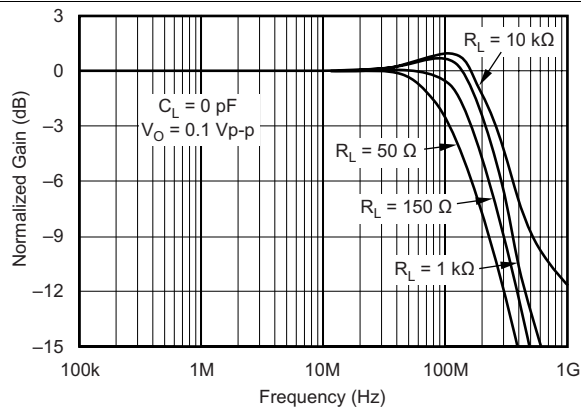


Figure 12. Frequency Response for Various R_L

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Typical Characteristics (continued)

$T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $G = 2$, $R_F = 604\ \Omega$, $R_L = 150\ \Omega$ connected to $V_S / 2$ (unless otherwise noted)

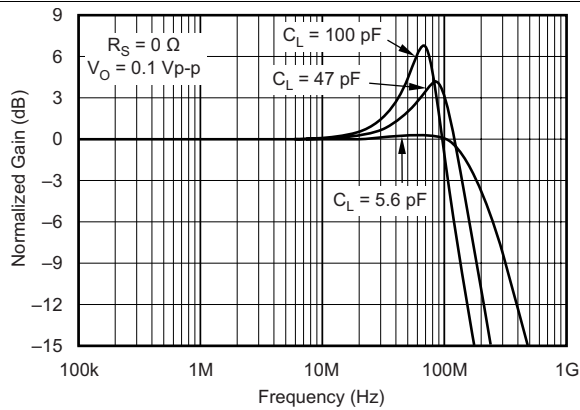


Figure 13. Frequency Response for Various C_L

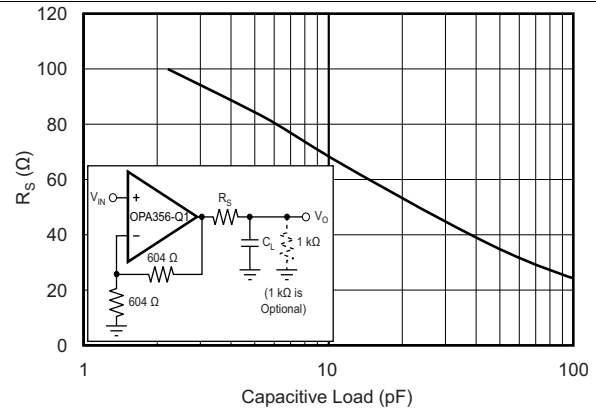


Figure 14. Recommended R_S vs Capacitive Load

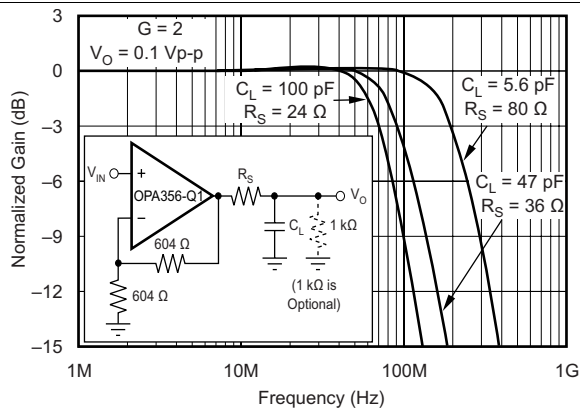


Figure 15. Frequency Response vs Capacitive Load

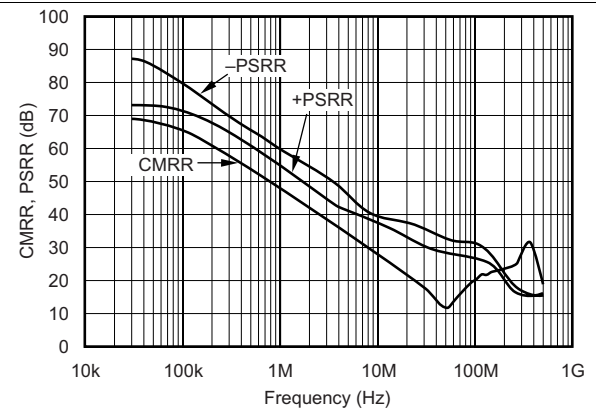


Figure 16. Common-Mode Rejection Ratio and Power-Supply Rejection Ratio vs Frequency

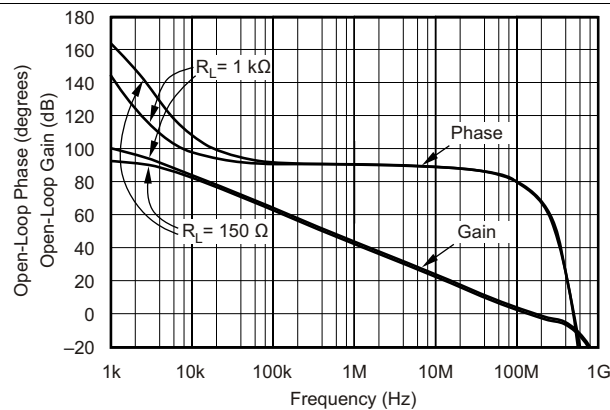


Figure 17. Open-Loop Gain and Phase

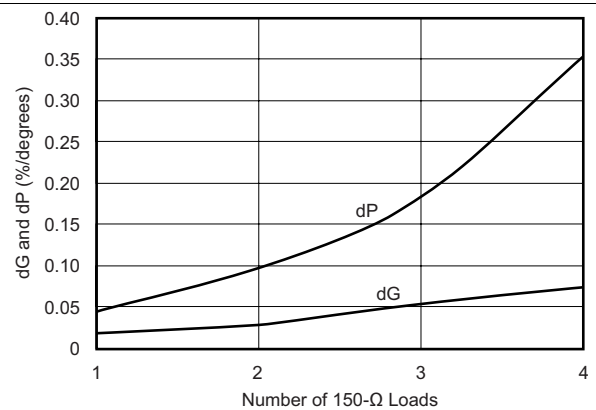


Figure 18. Composite Video Differential Gain and Phase

Typical Characteristics (continued)

$T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $G = 2$, $R_F = 604\ \Omega$, $R_L = 150\ \Omega$ connected to $V_S / 2$ (unless otherwise noted)

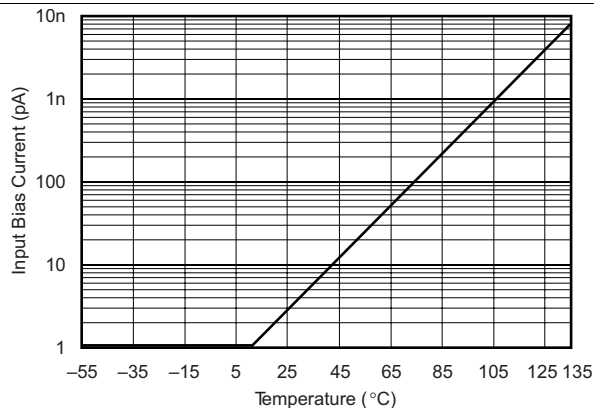


Figure 19. Input Bias Current vs Temperature

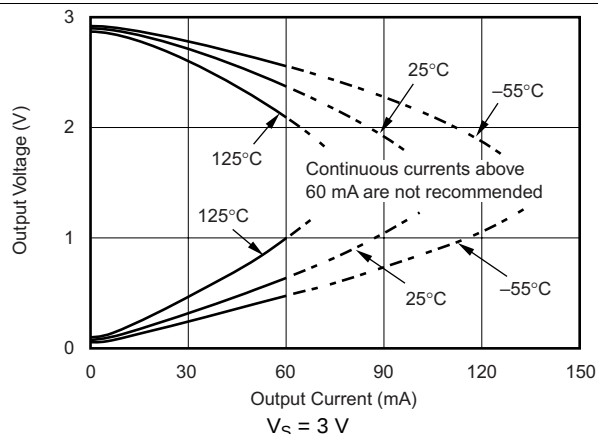


Figure 20. Output Voltage Swing vs Output Current

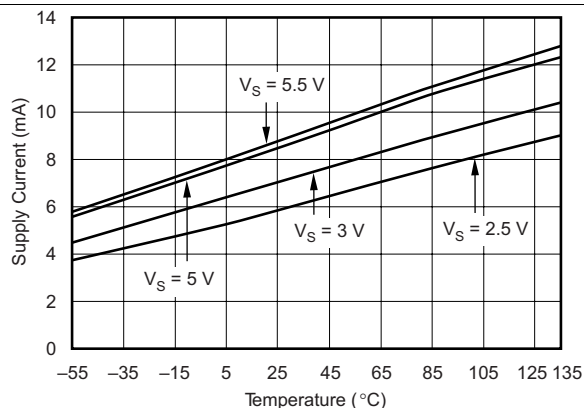


Figure 21. Supply Current vs Temperature

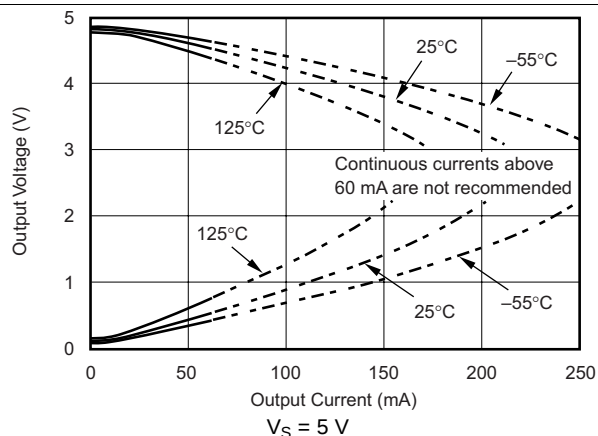


Figure 22. Output Voltage Swing vs Output Current

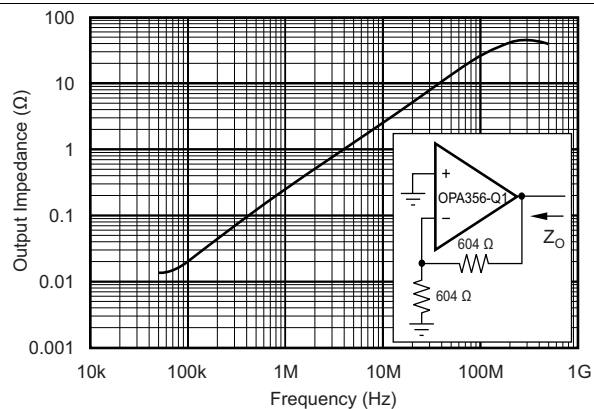


Figure 23. Closed-Loop Output Impedance vs Frequency

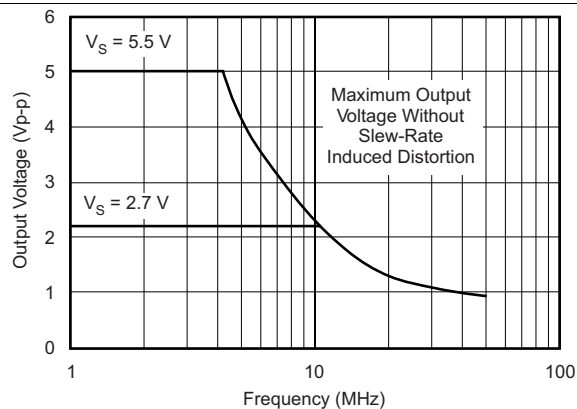


Figure 24. Maximum Output Voltage vs Frequency

Typical Characteristics (continued)

$T_A = 25^\circ\text{C}$, $V_S = 5\text{ V}$, $G = 2$, $R_F = 604\ \Omega$, $R_L = 150\ \Omega$ connected to $V_S / 2$ (unless otherwise noted)

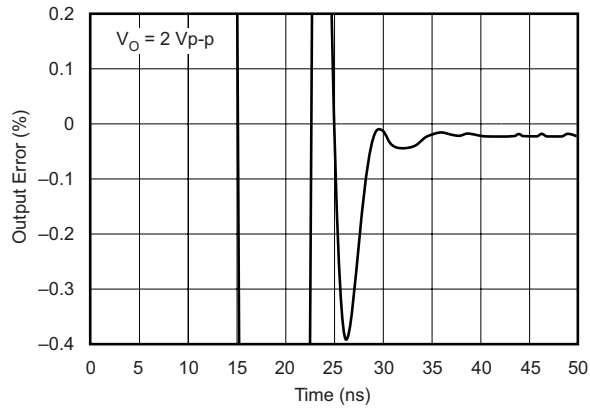


Figure 25. Output Settling Time to 0.1%

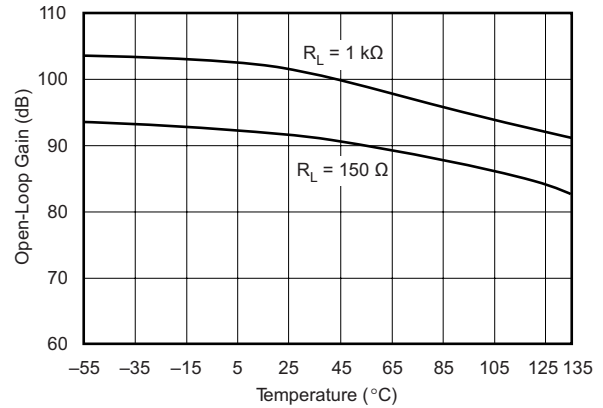


Figure 26. Open-Loop Gain vs Temperature

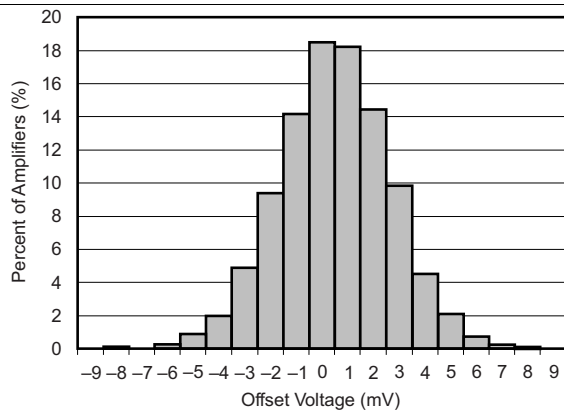


Figure 27. Offset Voltage Production Distribution

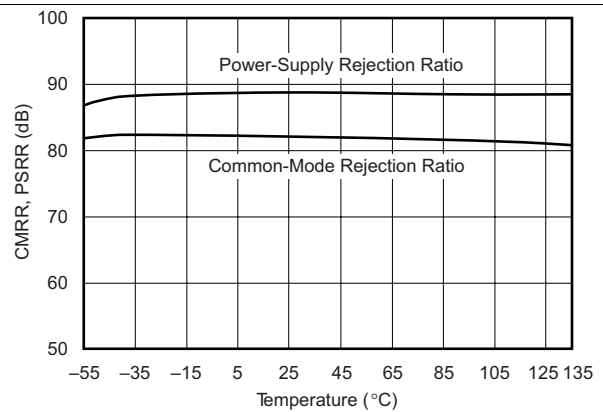


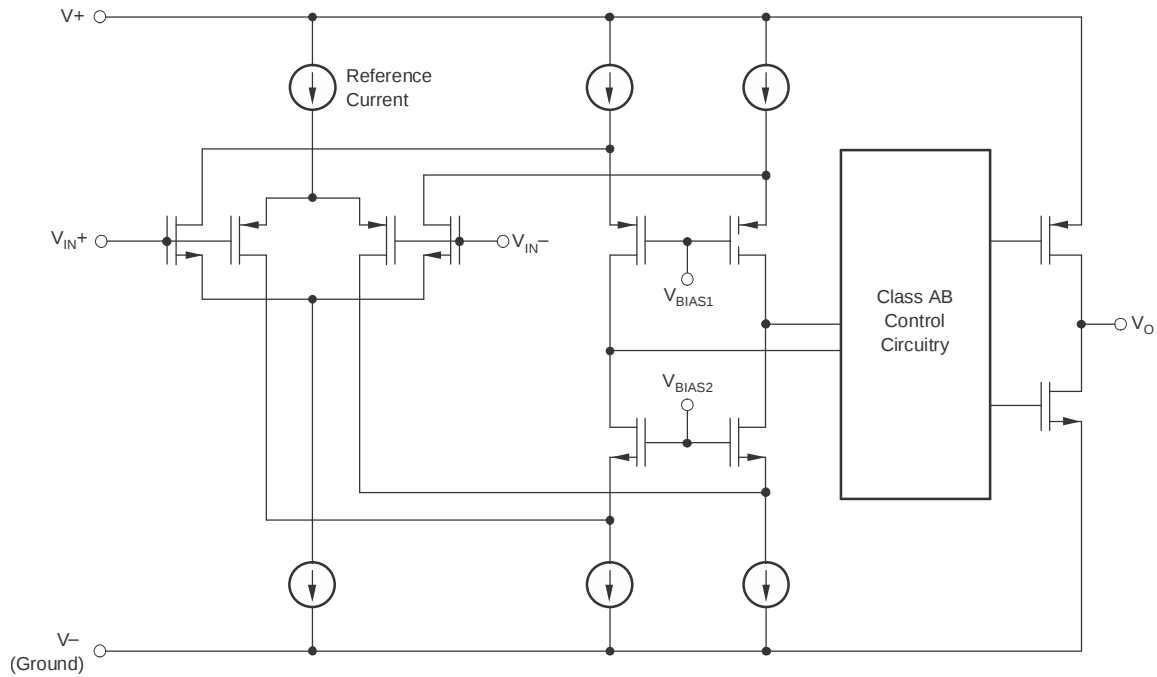
Figure 28. Common-Mode Rejection Ratio and Power-Supply Rejection Ratio vs Temperature

7 Detailed Description

7.1 Overview

The OPA356-Q1 operational amplifier is a high-speed, 360-V/ μ s, amplifier, making the device a great option for transimpedance applications. The device is unity-gain stable and can operate on a single-supply voltage (2.7 V to 5.5 V), or a split-supply voltage (± 1.35 V to ± 2.75 V), making the device highly versatile and simple to use. The OPA356-Q1 amplifier is specified from 2.7 V to 5.5 V and over the automotive temperature range of -40°C to $+125^{\circ}\text{C}$.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Operating Voltage

The OPA356-Q1 is specified over a power-supply range of 2.7 V to 5.5 V (± 1.35 V to ± 2.75 V). However, the supply voltage may range from 2.5 V to 5.5 V (± 1.25 V to ± 2.75 V). Supply voltages higher than 7.5 V (absolute maximum) can permanently damage the amplifier.

Parameters that vary significantly over supply voltage or temperature are shown in the [Typical Characteristics](#) section of this data sheet.

7.3.2 Output Drive

The output stage of the OPA356-Q1 is capable of driving a standard back-terminated 75- Ω video cable. A back-terminated transmission line does not exhibit a capacitive load to its driver. A properly back-terminated 75- Ω cable does not appear as capacitance; the cable presents only a 150- Ω resistive load to the OPA356-Q1 output.

The output stage can supply high short-circuit current (typically over 200 mA). Therefore, an on-chip thermal shutdown circuit is provided to protect the OPA356-Q1 from dangerously high junction temperatures. At 160°C, the protection circuit shuts down the amplifier. Normal operation resumes when the junction temperature cools to below 140°C.

NOTE

TI does not recommend running a continuous dc current in excess of ± 60 mA. See [Figure 20](#) in the [Typical Characteristics](#) section.

7.4 Device Functional Modes

The OPA356-Q1 is powered on when the supply is connected. The device can operate as a single-supply operational amplifier or dual-supply amplifier depending on the application. The device can also be used with asymmetrical supplies as long as the differential voltage (V_- to V_+) is at least 1.8 V and no greater than 5.5 V (for example, V_- is set to -3.5 V and V_+ is set to 1.5 V).

8 Application and Implementation

8.1 Application Information

The OPA356-Q1 is a CMOS, high-speed, voltage-feedback, operational amplifier (op-amp) designed for general-purpose applications.

The amplifier features a 200-MHz gain bandwidth and 300-V/μs slew rate, but the device is unity-gain stable and operates as a 1-V/V voltage follower.

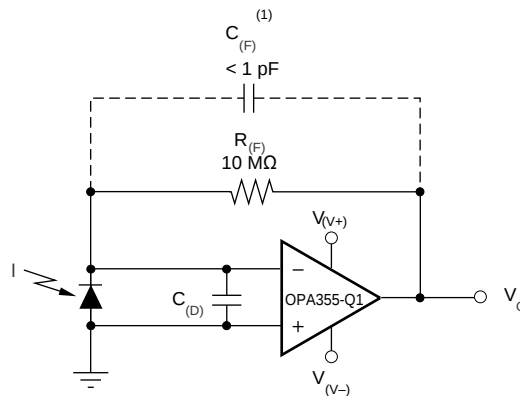
The input common-mode voltage range of the device includes ground, which allows the OPA356-Q1 to be used in virtually any single-supply application up to a supply voltage of 5.5 V.

8.2 Typical Applications

8.2.1 Transimpedance Amplifier

Wide gain bandwidth, low input bias current, low input voltage, and current noise make the OPA356-Q1 a preferred wideband photodiode transimpedance amplifier. Low-voltage noise is important because photodiode capacitance causes the effective noise gain of the circuit to increase at high frequency.

The key elements to a transimpedance design, as shown in Figure 29, are the expected diode capacitance ($C_{(D)}$), which must include the parasitic input common-mode and differential-mode input capacitance (4 pF + 5 pF), the desired transimpedance gain ($R_{(FB)}$), and the gain-bandwidth (GBW) for the OPA356-Q1 (20 MHz). With these three variables set, the feedback capacitor value ($C_{(FB)}$) is set to control the frequency response. $C_{(FB)}$ includes the stray capacitance of $R_{(FB)}$, which is 0.2 pF for a typical surface-mount resistor.



(1) $C_{(FB)}$ is optional to prevent gain peaking. $C_{(FB)}$ includes the stray capacitance of $R_{(FB)}$.

Figure 29. Dual-Supply Transimpedance Amplifier

8.2.1.1 Design Requirements

PARAMETER	VALUE
Supply voltage $V_{(V+)}$	2.5 V
Supply voltage $V_{(V-)}$	-2.5 V

8.2.1.2 Detailed Design Procedure

To achieve a maximally-flat, second-order Butterworth frequency response, the feedback pole must be set to:

$$\frac{1}{2 \times \pi \times R_{(FB)} \times C_{(FB)}} = \sqrt{\frac{GBW}{4 \times \pi \times R_{(FB)} \times C_{(D)}}} \quad (1)$$

Use Equation 2 to calculate the bandwidth.

$$f_{(-3 \text{ dB})} = \sqrt{\frac{GBW}{2 \times \pi \times R_{(FB)} \times C_{(D)}}} \quad (2)$$

For other transimpedance bandwidths, consider the high-speed CMOS [OPA380](#) (90-MHz GBW), [OPA354](#) (100-MHz GBW), [OPA300](#) (180-MHz GBW), [OPA355](#) (200-MHz GBW), or [OPA656](#) and [OPA657](#) (400-MHz GBW).

For single-supply applications, the +INx input can be biased with a positive DC voltage to allow the output to reach true zero when the photodiode is not exposed to any light, and respond without the added delay that results from coming out of the negative rail; this configuration is shown in [Figure 30](#). This bias voltage appears across the photodiode, providing a reverse bias for faster operation.

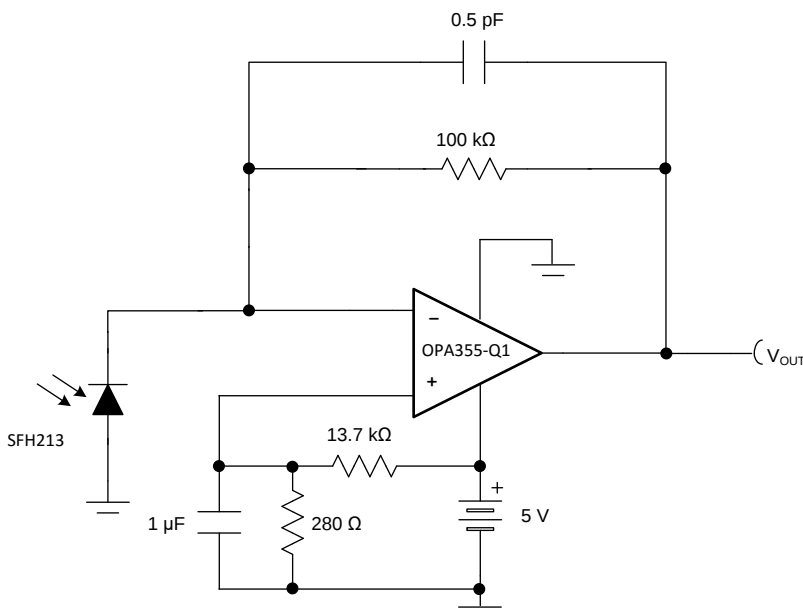


Figure 30. Single-Supply Transimpedance Amplifier

For additional information, see the [Compensate Transimpedance Amplifiers Intuitively](#) application bulletin.

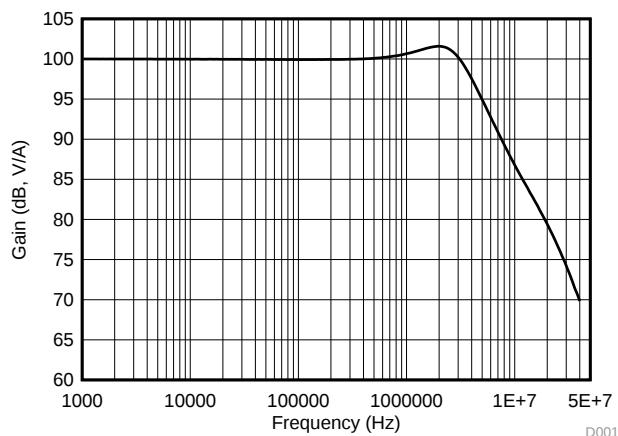
8.2.1.2.1 Optimizing The Transimpedance Circuit

To achieve the best performance, select components according to the following guidelines:

1. For lowest noise, select $R_{(FB)}$ to create the total required gain. Using a lower value for $R_{(FB)}$ and adding gain after the transimpedance amplifier generally produces poorer noise performance. The noise produced by $R_{(FB)}$ increases with the square-root of $R_{(FB)}$, whereas the signal increases linearly. Therefore, signal-to-noise ratio improves when all the required gain is placed in the transimpedance stage.
2. Minimize photodiode capacitance and stray capacitance at the summing junction (inverting input). This capacitance causes the voltage noise of the op amp to amplify (increasing amplification at high frequency). Using a low-noise voltage source to reverse-bias a photodiode can significantly reduce the capacitance. Smaller photodiodes have lower capacitance. Use optics to concentrate light on a small photodiode.
3. Noise increases with increased bandwidth. Limit the circuit bandwidth to only that required. Use a capacitor across the $R_{(FB)}$ to limit bandwidth, even if not required for stability.
4. Circuit board leakage can degrade the performance of an otherwise well-designed amplifier. Clean the circuit board carefully. A circuit board guard trace that encircles the summing junction and is driven at the same voltage can help control leakage.

For additional information, see the [Noise Analysis of FET Transimpedance Amplifiers](#) and [Noise Analysis for High-Speed Op Amps](#) application bulletins).

8.2.1.3 Application Curve



–3 dB bandwidth is 4.56 MHz

Figure 31. AC Transfer Function

8.2.2 High-Impedance Sensor Interface

Many sensors have high source impedances that may range up to 10 MΩ, or even higher. The output signal of sensors often must be amplified or otherwise conditioned by means of an amplifier. The input bias current of this amplifier can load the sensor output and cause a voltage drop across the source resistance, as shown in Figure 32, where $V_{(+INx)} = V_S - I_{(BIAS)} \times R_{(S)}$. The last term, $I_{(BIAS)} \times R_{(S)}$, shows the voltage drop across $R_{(S)}$. To prevent errors introduced to the system as a result of this voltage, an op amp with very low input bias current must be used with high impedance sensors. This low current keeps the error contribution by $I_{(BIAS)} \times R_{(S)}$ less than the input voltage noise of the amplifier, so that the input voltage noise does not become the dominant noise factor. The OPA356-Q1 op amp features very low input bias current (typically 200 fA), and is therefore a preferred choice for such applications.

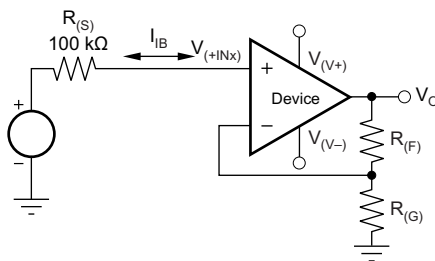
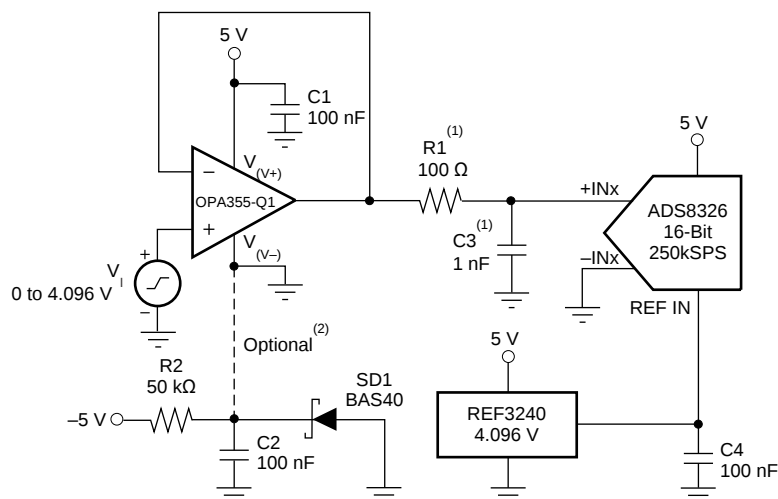


Figure 32. Noise as a Result of $I_{(BIAS)}$

8.2.3 Driving ADCs

The OPA356-Q1 op amps are designed for driving sampling analog-to-digital converters (ADCs) with sampling speeds up to 1 MSPS. The zero-crossover distortion input stage topology allows the OPA356-Q1 to drive ADCs without degradation of differential linearity and THD.

The OPA356-Q1 can be used to buffer the ADC switched input capacitance and resulting charge injection while providing signal gain. [Figure 33](#) shows the OPA356-Q1 configured to drive the [ADS8326](#).



(1) Suggested value; may require adjustment based on specific application.

(2) Single-supply applications lose a small number of ADC codes near ground as a result of op amp output swing limitation. If a negative power supply is available, this simple circuit creates a -0.3 V supply to allow output swing to true ground potential.

Figure 33. Driving the ADS8326

8.2.4 Active Filter

The OPA356-Q1 is designed for active filter applications that require a wide bandwidth, fast slew rate, low-noise, single-supply operational amplifier. [Figure 34](#) depicts a 500-kHz, second-order, low-pass filter using the multiple-feedback (MFB) topology. The components are selected to provide a maximally-flat Butterworth response. Beyond the cutoff frequency, roll-off is -40 dB/dec . The Butterworth response is preferred for applications requiring predictable gain characteristics, such as the anti-aliasing filter used in front of an ADC.

One point to observe when considering the MFB filter is that the output is inverted, relative to the input. If this inversion is not required, or not desired, a noninverting output can be achieved through one of the following options:

1. Adding an inverting amplifier
2. Adding an additional second-order MFB stage
3. Using a noninverting filter topology, such as the Sallen-Key (see [Figure 35](#)).

MFB and Sallen-Key, low-pass and high-pass filter synthesis is quickly accomplished using TI's [FilterPro™](#) program. This software is available as a free download at www.ti.com.

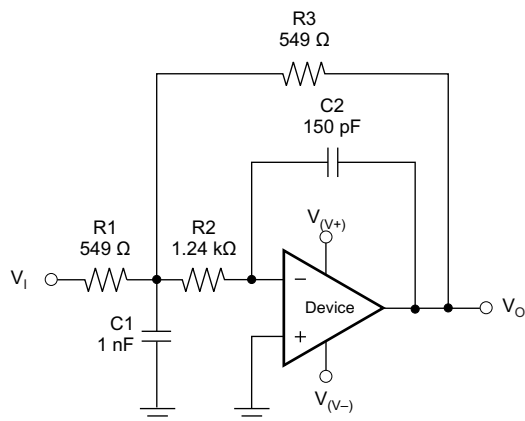


Figure 34. Second-Order Butterworth 500-kHz Low-Pass Filter

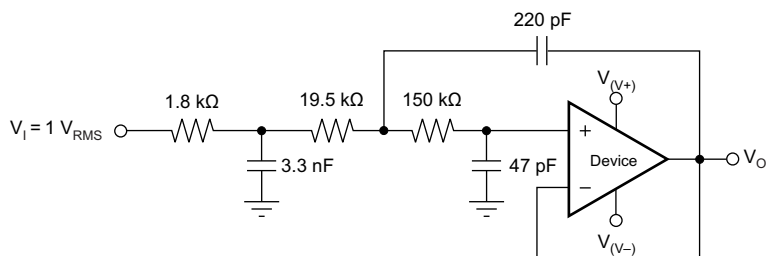


Figure 35. OPA356-Q1 Configured as a Three-Pole, 20-kHz, Sallen-Key Filter

9 Power Supply Recommendations

The OPA356-Q1 is specified for operation from 2.7 to 5.5 V (± 1.35 to ± 2.75 V); many specifications apply from -40°C to $+125^{\circ}\text{C}$. Parameters that can exhibit significant variance with regard to operating voltage or temperature are shown in the [Typical Characteristics](#) section.

Place 0.1- μF bypass capacitors close to the power-supply pins to reduce errors coupling in from noisy or high-impedance power supplies. For more detailed information on bypass capacitor placement, see the [Layout Guidelines](#) section.

Power dissipation depends on power-supply voltage, signal and load conditions. With DC signals, power dissipation is equal to the product of output current times the voltage across the conducting output transistor, $V_S - V_O$. Minimize power dissipation by using the lowest possible power-supply voltage required to ensure the required output voltage swing.

For resistive loads, the maximum power dissipation occurs at a DC output voltage of one-half the power-supply voltage. Dissipation with AC signals is lower. Application bulletin AB-039, *Power Amplifier Stress and Power Handling Limitations* explains how to calculate or measure power dissipation with unusual signals and loads, and is available on www.ti.com.

Any tendency to activate the thermal protection circuit indicates excessive power dissipation or an inadequate heat sink. For reliable operation, limit junction temperature to 150°C maximum. To estimate the margin of safety in a complete design, increase the ambient temperature to trigger the thermal protection at 160°C . The thermal protection must trigger more than 35°C above the maximum expected ambient condition of the application.

10 Layout

10.1 Layout Guidelines

- Good high-frequency PC board layout techniques should be employed for the OPA356-Q1. Generous use of ground planes, short direct signal traces, and a suitable bypass capacitor located at the V+ pin assure clean, stable operation. Large areas of copper also provide a means of dissipating heat that is generated within the amplifier in normal operation.
- Sockets are definitely not recommended for use with any high-speed amplifier.
- A 10- μ F ceramic bypass capacitor is the minimum recommended value; adding a 1- μ F or larger tantalum capacitor in parallel can be beneficial when driving a low-resistance load. Providing adequate bypass capacitance is essential to achieving very low harmonic and intermodulation distortion.

10.2 Layout Example

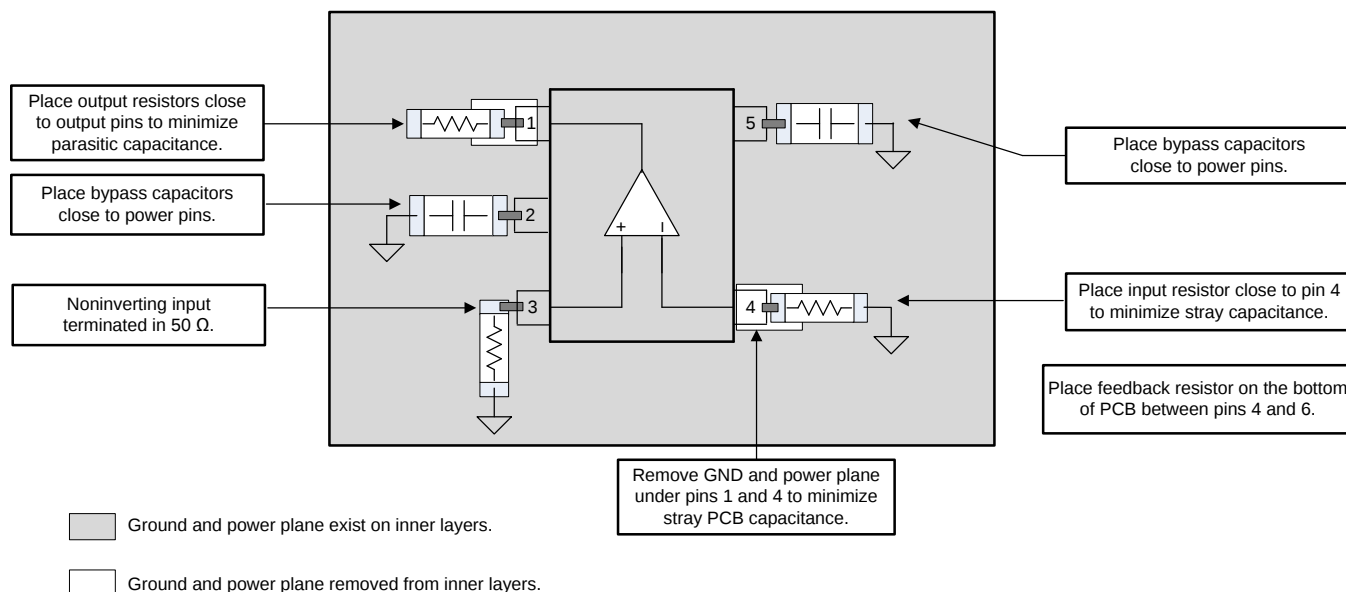


Figure 36. Example Layout

11 デバイスおよびドキュメントのサポート

11.1 ドキュメントのサポート

11.1.1 関連資料

関連資料については、以下を参照してください。

- 『OPA380 高精度、高速トランスインピーダンス・アンプ』
- 『OPA354 250MHz、レール・ツー・レールI/O、CMOS オペアンプ』
- 『OPA300 低ノイズ、高速、16ビット高精度、CMOS オペアンプ』
- 『OPA355 200MHz、CMOS オペアンプ、シャットダウン付き』
- 『OPA656 広帯域、ユニティ・ゲイン安定、FET 入力オペアンプ』
- 『OPA657 1.6GHz、低ノイズ、FET 入力オペアンプ』
- 『トランスインピーダンス・アンプの直感的な補正』
- 『FET トランスインピーダンス・アンプのノイズ解析』
- 『高速オペアンプのノイズ解析』
- 『ADS8326 16ビット、高速、2.7V~5.5V、マイクロパワー・サンプリングA/Dコンバータ』
- FilterPro™

11.2 ドキュメントの更新通知を受け取る方法

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11.6 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

12 メカニカル、パッケージ、および注文情報

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
OPA356AQDBVRQ1	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OOVQ
OPA356AQDBVRQ1.B	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OOVQ

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF OPA356-Q1 :

- Catalog : [OPA356](#)

NOTE: Qualified Version Definitions:

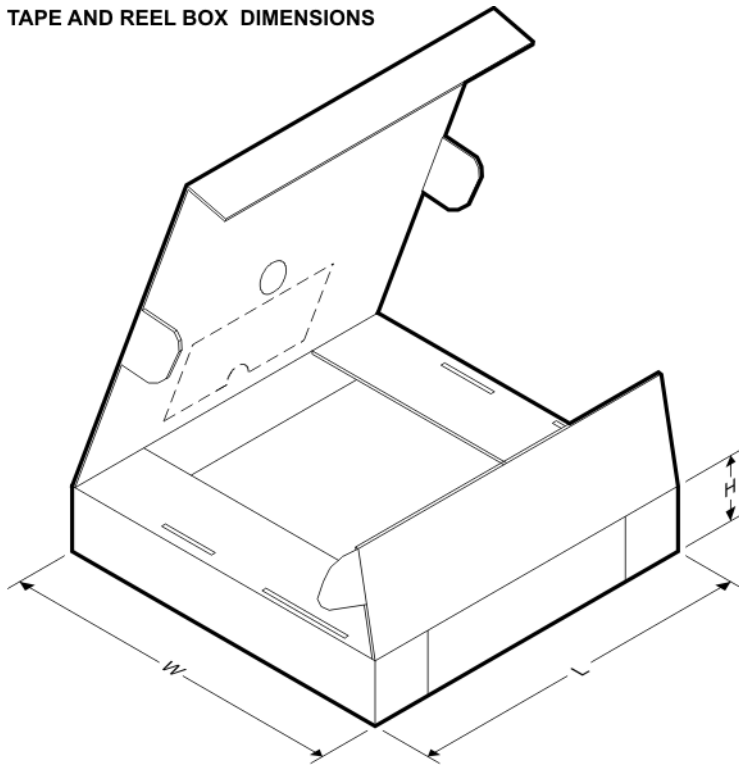
- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA356AQDBVRQ1	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA356AQDBVRQ1	SOT-23	DBV	5	3000	190.0	190.0	30.0



SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-178.
4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
5. Support pin may differ or may not be present.

EXAMPLE BOARD LAYOUT

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

4214839/K 08/2024

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214839/K 08/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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